Chip back potential is the level which bulk silicon is maintained by on-chip connection, or it is the level to which the chip back must be connected when specifically stated below. If no potential is given the chip back should be isolated.

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**Top Material: Al**

**Backside Material: Ti/Ni/Ag**

**Bond Pad Size: .004” X .004”**

**Backside Potential: Cathode**

**Mask Ref:**

**APPROVED BY: DK DIE SIZE .120” X .120” DATE: 9/21/21**

**MFG: MOTOROLA / ON SEMI THICKNESS .025” P/N: MURC1520**

**DG 10.1.2**

#### Rev B, 7/19/02